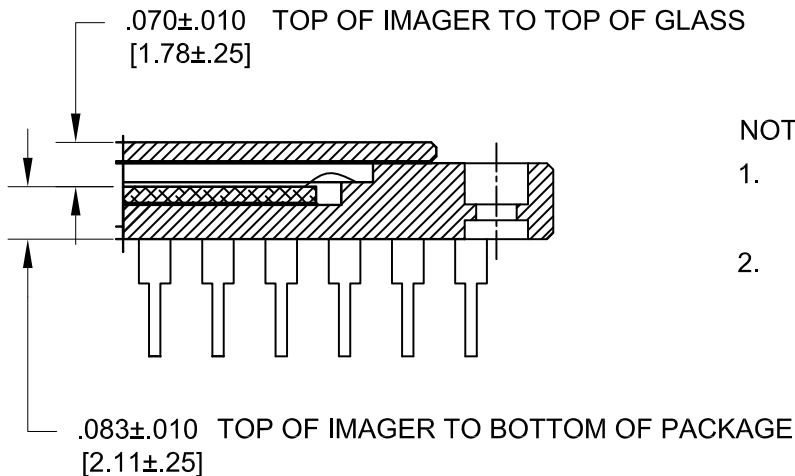
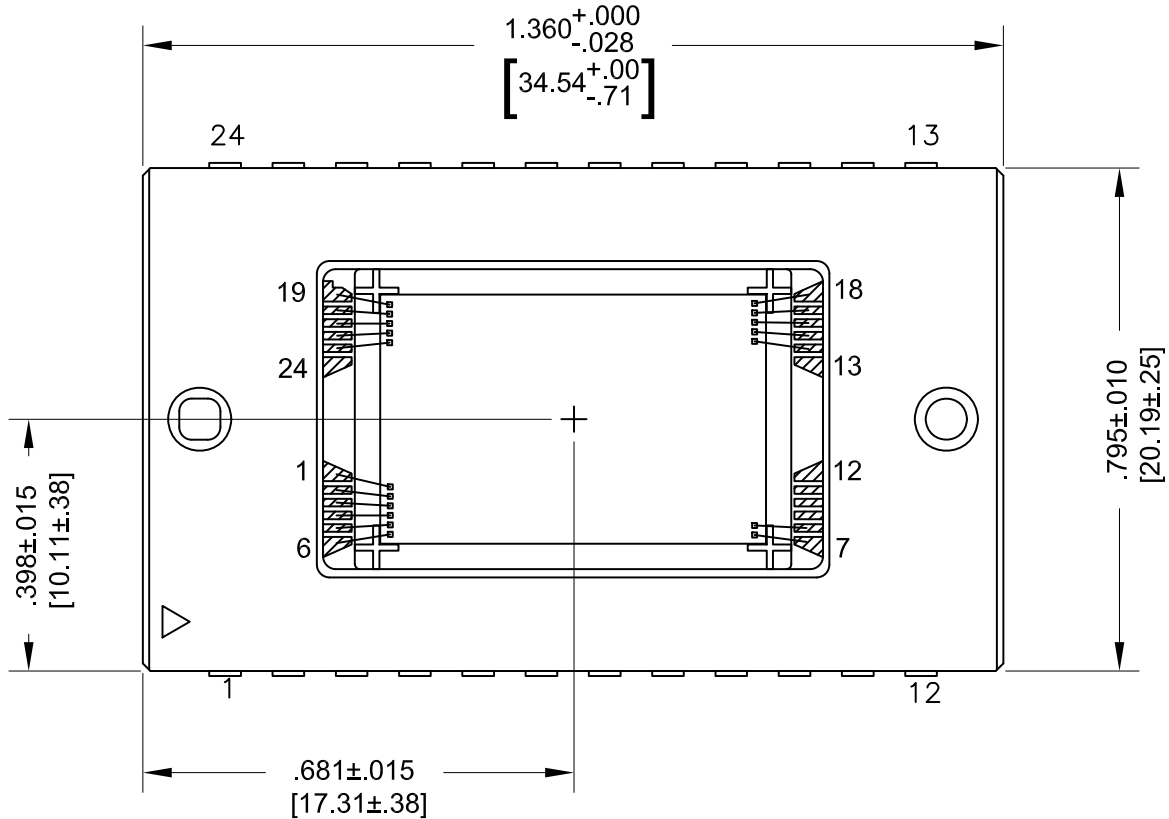


CERAMIC DIP 24
CASE 125AU
ISSUE O

DATE 30 JUN 2014



NOTES:

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY (0.04,0.00)mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN ± 2° OF ANY PACKAGE CAVITY EDGE.

Dimensions in: Inches [mm]

| | | |
|-------------------------|-----------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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